

EAST Search History

JWS

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	360	((DECAPSULAT\$4 OR ((VARNISH OR LACQUER PLASTIC OR RESIN OR PLASTIC OR EPOXY OR ENCAPSULANT\$4) NEAR3 (REMOV\$4 OR DISSOLV\$4 OR STRIP\$4 OR PEEL\$4))) NEAR8 (WAFER OR SEMICONDUCTOR OR SUBSTRATE OR "CIRCUIT BOARD" OR (INTEGRATED NEAR1 CIRCUIT) OR ELECTRONICS)) AND ((CHEMICAL OR SOLUTION OR FORMULATION OR SOLVENT OR ACID OR ETCHANT OR STRIPPER) NEAR8 ((HEAT OR TEMPERATURE) NEAR5 (ACTIVAT\$4 OR REACT\$4 OR REACTIV\$4 OR SENSITIV\$4)))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/04/01 01:32
L4	60	DECAPSULAT\$4 AND ((CHEMICAL OR SOLUTION OR FORMULATION OR SOLVENT OR ACID OR ETCHANT OR STRIPPER) NEAR8 ((HEAT OR TEMPERATURE) NEAR5 (ACTIVAT\$4 OR REACT\$4 OR REACTIV\$4 OR SENSITIV\$4)))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/04/01 01:35

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JWS

L7	112	((DECAPSULAT\$4 OR ((VARNISH OR LACQUER PLASTIC OR RESIN OR PLASTIC OR EPOXY OR ENCAPSULANT\$4) NEAR3 (REMOV\$4 OR DISSOLV\$4 OR STRIP\$4 OR PEEL\$4))) NEAR8 (WAFER OR SEMICONDUCTOR OR SUBSTRATE OR "CIRCUIT BOARD" OR (INTEGRATED NEAR1 CIRCUIT) OR ELECTRONICS)) AND ((SOLVENT OR ACID OR STRIPPER OR SOLUTION OR CHEMICAL OR FORMULATION) NEAR8 (HEATED OR HOT OR THERMAL\$4 OR HEATER OR WARM\$4) NEAR8 (GAS OR AIR OR NITROGEN))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/04/01 01:54
L10	639	((DECAPSULAT\$4 OR ((VARNISH OR LACQUER PLASTIC OR RESIN OR PLASTIC OR EPOXY OR ENCAPSULANT\$4) NEAR3 (REMOV\$4 OR DISSOLV\$4 OR STRIP\$4 OR PEEL\$4))) NEAR8 (WAFER OR SEMICONDUCTOR OR SUBSTRATE OR "CIRCUIT BOARD" OR (INTEGRATED NEAR1 CIRCUIT) OR ELECTRONICS)) AND ((GAS OR AIR OR NITROGEN) NEAR5 (HEATED OR HOT OR THERMAL\$4 OR HEATER OR WARM\$4))	USPAT; USOCR; IBM_TDB	OR	ON	2007/04/01 03:14

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L17	120	((DECAPSULAT\$4 OR ((VARNISH OR LACQUER PLASTIC OR RESIN OR PLASTIC OR EPOXY OR ENCAPSULANT\$4) NEAR3 (REMOV\$4 OR DISSOLV\$4 OR STRIP\$4 OR PEEL\$4))) NEAR8 (WAFER OR SEMICONDUCTOR OR SUBSTRATE OR "CIRCUIT BOARD" OR (INTEGRATED NEAR1 CIRCUIT) OR ELECTRONICS)) AND ((GAS OR AIR OR NITROGEN) NEAR5 (HEATED OR HOT OR THERMAL\$4 OR HEATER OR WARM\$4)) AND (ACID NEAR4 (SULFURIC OR NITRIC))	USPAT; USOCR; IBM_TDB	OR	ON	2007/04/01 03:19
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EAST Search History

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Ref #	Hits	Search Query	DBs	Default Operat or	Plural s	Time Stamp
L52	67	((DECAPSULAT\$4 OR ((VARNISH OR LACQUER PLASTIC OR RESIN OR PLASTIC OR EPOXY OR ENCAPSULANT\$4) NEAR3 (REMOV\$4 OR DISSOLV\$4 OR STRIP\$4 OR PEEL\$4))) NEAR8 (WAFER OR SEMICONDUCTOR OR SUBSTRATE OR "CIRCUIT BOARD" OR (INTEGRATED NEAR1 CIRCUIT))) AND ((SOLVENT OR ACID OR STRIPPER OR SOLUTION OR CHEMICAL OR FORMULATION) NEAR8 (DROP OR PUDDLE OR POOL GLOBULE OR DROPLETS)) AND ((GAS OR AIR OR NITROGEN) NEAR5 (HEATED OR HOT OR THERMAL\$4 OR HEATER OR WARM\$4))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/04/01 00:59

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JHS

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L50	216	((DECAPSULAT\$4 OR ((VARNISH OR LACQUER PLASTIC OR RESIN OR PLASTIC OR EPOXY) NEAR3 (REMOV\$4 OR DISSOLV\$4 OR STRIP\$4))) NEAR8 (WAFER OR SEMICONDUCTOR OR SUBSTRATE OR "CIRCUIT BOARD" OR (INTEGRATED NEAR1 CIRCUIT))) AND ((SOLVENT OR ACID OR STRIPPER OR SOLUTION OR CHEMICAL OR FORMULATION) NEAR8 (DROP OR PUDDLE OR POOL GLOBULE OR DROPLETS))	US-PGPU B; USPAT; USOCR; EPO; JPO; DERWEN T; IBM_TDB	OR	ON	2007/04/01 00:57